

REMARKS

Claims 1-25 are pending in the application.

Claims 14-25 are allowed.

Claims 1-4, 8, 9, 12 and 13 are rejected.

Claims 5-7, 10 and 11 are objected to.

Claims 1-4, 8-9 and 12-13 are rejected under 35 U.S.C. 102(b).

No new matter is added.

Claims 1-25 remain in the case for consideration upon entry of this amendment.

Applicant requests reconsideration and allowance of the claims in light of the above amendments and following remarks.

Claims Rejections – 35 U.S.C. § 102

Claims 1-4, 8-9 and 12-13 are rejected under 35 U.S.C. 102(b) as being anticipated by Kang, et al.

Claim 1 is amended hereby more definitely and distinctly to claim the invention. No new matter is added, as the amended language is found throughout the specification including the drawings, particularly at page 6, lines 21-30 and page 8, line 23 through page 9, line 2 and Figs. 4 and 9 (the latter of which, it will be remembered, shows the pre-alignment socket guider and the alignment package guider mounted thereon upside down from the normal orientation (see Figs. 5 and 8).

Claim 1 now particularly claims the pre-alignment of the socket and its aligned cover with the head assembly by way of the novel, downwardly disposed socket guider that mounts an upwardly disposed package guider that thereafter aligns the semiconductor package: “a pick-and-place tool structured to load/unload the semiconductor package; a head assembly coupled with the pick-and-place tool; and a socket underneath the head assembly, the socket being configured to connect the semiconductor package loaded by the pick-and-place tool and the head assembly to a tester, the head assembly including an upwardly disposed package guider configured automatically to align the semiconductor package as the package is released by and falls from the pick-and-place tool, and a downwardly disposed socket guider mounting the upwardly disposed package guider, the socket guider configured automatically to pre-align the head assembly with a position of the socket by downward contact between the socket guider and a socket cover connected with the socket before operation of the package guider, the socket aligned with and positioned under the socket cover.”

Kang contains no such teachings of double alignment, since Kang is of the type of package aligner applicants discuss in their Background as involving only package-to-socket alignment (see Figs. 1-2), *not the novel combination of socket-to-head pre-alignment and package-to-socket alignment*. Thus, while Kang represents a recent improvement for package-to-socket alignment, Kang and the other known prior art is utterly mute about the claimed combination.

Kang simply teaches a narrowed throat or guide 108 that centers semiconductor package 116 over socket cover 204 for centering the package therein. Kang teaches nothing about a socket guider structure that mounts such a package guider for pre-aligning such a package guider with the head assembly before the package free-falls through the package guidance structure and, by downward contact with a socket cover, into the socket.

Accordingly, applicants submit that amended claim 1 is allowable, as are those claims 2-4, 8-9 and 12-13 depending therefrom.

Claim Objections

Claims 5-7 and 10-11 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. Without conceding the Examiner's rejections of base claims 5 and 10, applicants hereby amend claims 5, 10 and 11 to render them allowable, along with claims 6 and 7 depending from allowable claim 5.

Allowable Subject Matter

Claims 14-25 are allowed over the prior art of the record.

Conclusion

Accordingly, all claims are deemed allowable.

For the foregoing reasons, reconsideration and allowance of claims 1-25 of the application, as amended, is solicited. The Examiner is encouraged to telephone the undersigned at (503) 222-3613 if it appears that an interview would be helpful in advancing the case.

Respectfully submitted,
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